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IN THE SPECIFICATION

The recital of "o-cresol" has been corrected as per the Examiner's suggestion.

The Examiner requests that a statement regarding the PCT Application be inserted at the

beginning of the application.

Please delete the original priority statement and insert the following immediately before the

"Field of the Subject Matter":

"This application claims priority to United States Provisional Application Serial Number

60/488484 filed on July 17, 2003 and Patent Cooperation Treaty Application Serial No.:

PCT/US03/34347 filed on October 27, 2003, which are both commonly owned and

incorporated herein in their entirety."

The Examiner objects to the Brief Description of the Figures as not containing a listing of

the tables. There is no new matter added by virtue of this amendment.

Please replace the original Brief Description of the Figures with the following:

"BRIEF DESCRIPTION OF THE FIGURES & TABLES

Figure 1 shows a fluid property comparison for two contemplated planarization

compositions.

Figure 2 shows structural information for a contemplated planarization composition.

Figure 3 shows structural information for a contemplated planarization composition.

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Figure 4 shows planarization performance of a contemplated planarization composition.

Figure 5 shows planarization performance of a contemplated planarization composition.

Figure 6 shows planarization performance of a contemplated planarization composition.

Figure 7 shows planarization performance of a contemplated planarization composition,

Figure 8 shows plasma etch rates of a contemplated planarization composition.

Figure 9 shows fill and planarization data for a contemplated planarization composition.

Figure 10 shows fill and planarization data for a contemplated planarization composition.

Figure 11 shows profilometer results for a contemplated planarization composition.

Table 1 shows the structural information for the composition once the starting composition has been deposited onto a surface or wafer and baked and/or cured.

Table 2 shows the planarization performance for the Accuflo™ 2025 composition tested in two different laboratories.

Table 3 shows the planarization performance for the Accuflo™ 2025 composition tested in two different laboratories.

Table 4 shows show the planarization performance for the Accuflo™ 2025 composition tested in two different laboratories.

Table 5 shows the planarization performance for the Accuflo™ 2025 composition tested in two different laboratories

Table 6 shows the planarization performance for the Accuflo™ 2025 composition tested in two different laboratories.

Table 7 shows the planarization performance for the Accuflo™ 2025 composition tested in two different laboratories

Table 8 shows the planarization performance for the Accuflo™ 2027 composition tested in two different laboratories

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Table 9 shows the planarization performance for the Accuflo™ 2027 composition tested in two different laboratories

Table 10 shows the planarization performance for the Accuflo™ 2027 composition tested in two different laboratories.

Table 11 shows the planarization performance for the Accuflo™ 2027 composition tested in two different laboratories.

Table 12 shows the planarization performance for the Accuflo™ 2027 composition tested in two different laboratories.

Table 13 shows the planarization performance for the Accuflo™ 2027 composition tested in two different laboratories.

Table 14 shows the TMAH solvent resistance of the Accuflo™ 2027 when baked at about 160°C to about 230°C for about 90 seconds in ambient air.

Table 15 shows a planarization comparison between two contemplated compositions.

Table 16 shows the SEM cross section results for contemplated compounds.

Table 17 shows the BOE etch results for this same composition shown in Table 16."